

C3D06060A Silicon Carbide Schottky Diode Z-REC® RECTIFIER

\mathbf{V}_{RRM} = 600 V $\mathbf{I}_{F}(\mathbf{T}_{c}=135^{\circ}\mathbf{C})$ = 9 A \mathbf{Q}_{c} = 15 nC

Features

- 600-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- · Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- · Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives

Package







TO-220-2



Part Number	Package	Marking	
C3D06060A	TO-220-2	C3D06060	

Maximum Ratings (T_c = 25 °C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{RRM}	Repetitive Peak Reverse Voltage	600	٧		
V _{RSM}	Surge Peak Reverse Voltage	600	٧		
V _{DC}	DC Blocking Voltage	600	٧		
I _F	Continuous Forward Current	19 9 6	А	T _c =25°C T _c =135°C T _c =154°C	Fig. 3
I _{FRM}	Repetitive Peak Forward Surge Current	30 20	А	T_c =25°C, t_p = 10 ms, Half Sine Wave T_c =110°C, t_p = 10 ms, Half Sine Wave	
I _{FSM}	Non-Repetitive Peak Forward Surge Current	63 49	А	T_c =25°C, t_p = 10 ms, Half Sine Wave T_c =110°C, t_p = 10 ms, Half Sine Wave	Fig. 8
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	540 460	А	T_c =25°C, t_p = 10 μ s, Pulse T_c =110°C, t_p = 10 μ s, Pulse	Fig. 8
P _{tot}	Power Dissipation	88 38	W	T _c =25°C T _c =110°C	Fig. 4
T_{J} , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	°C		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



Electrical Characteristics

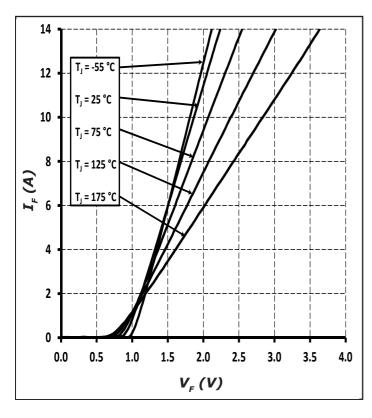
Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.5 2.0	1.7 2.4	V	I _F = 6 A T _J =25°C I _F = 6 A T _J =175°C	Fig. 1
I _R	Reverse Current	6.5 13	33 132	μΑ	V _R = 600 V T _J =25°C V _R = 600 V T _J =175°C	Fig. 2
Q _c	Total Capacitive Charge	15		nC	$V_R = 400 \text{ V, } I_F = 6 \text{ A}$ $di/dt = 500 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	Fig. 5
С	Total Capacitance	295 28.5 25.5		pF	V _R = 0 V, T _J = 25°C, f = 1 MHz V _R = 200 V, T _J = 25°C, f = 1 MHz V _R = 400 V, T _J = 25°C, f = 1 MHz	Fig. 6
E _c	Capacitance Stored Energy	2.3		μJ	V _R = 400 V	Fig. 7

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit	Note
$R_{_{ heta JC}}$	Thermal Resistance from Junction to Case	1.7	°C/W	Fig. 9

Typical Performance





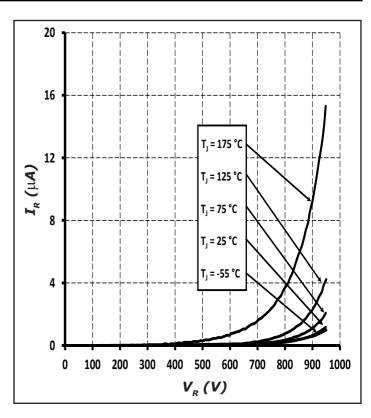
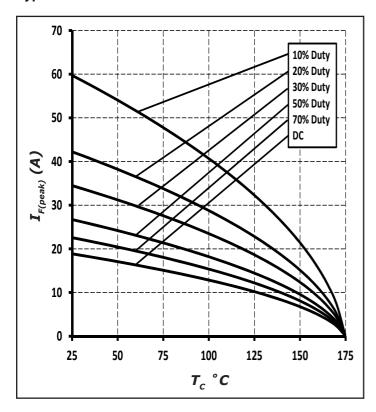


Figure 2. Reverse Characteristics



Typical Performance



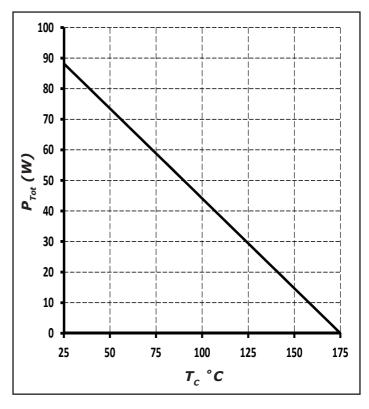


Figure 3. Current Derating

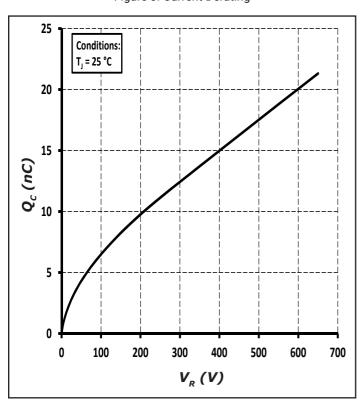


Figure 5. Total Capacitance Charge vs. Reverse Voltage

Figure 4. Power Derating

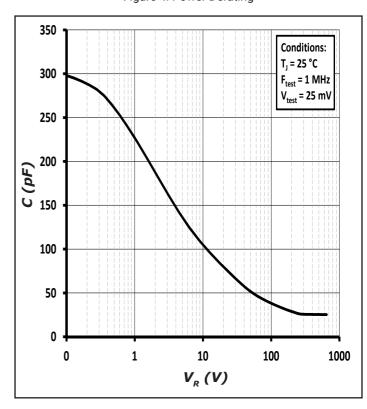
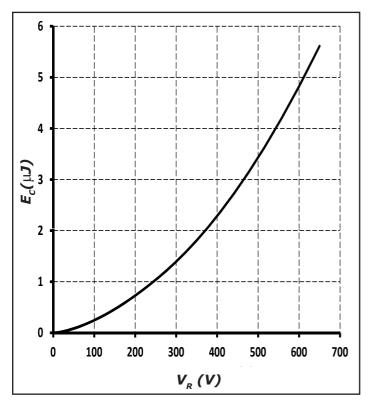


Figure 6. Capacitance vs. Reverse Voltage



Typical Performance



T_j = 25 °C
T_j = 110 °C

1,000

Figure 7. Capacitance Stored Energy

Figure 8. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)

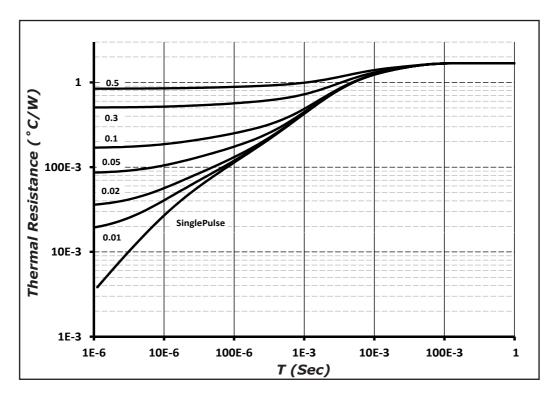
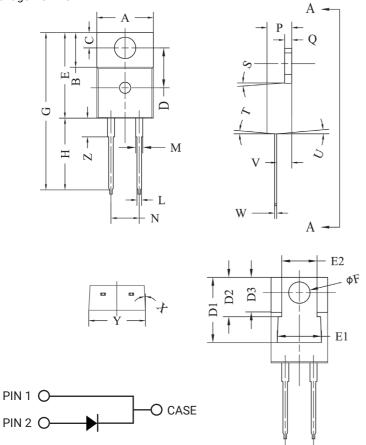


Figure 9. Transient Thermal Impedance



Package Dimensions

Package TO-220-2

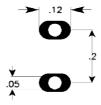


DO0	Inc	hes	Millimeters		
POS	Min	Max	Min	Max	
А	.381	.410	9.677	10.414	
В	.235	.255	5.969	6.477	
С	.100	.120	2.540	3.048	
D	.223	.337	5.664	8.560	
D1	.457	490	11.60-1	2.45 typ	
D2	.2773	803 typ	7.04-7.70 typ		
D3	.2442	252 typ	6.22-6	.4 typ	
E	.590	.615	14.986	15.621	
E1	.302	.326	7.68	8.28	
E2	.227	251	5.77	6.37	
F	.143	.153	3.632	3.886	
G	1.105	1.147	28.067	29.134	
Н	.500	.550	12.700	13.970	
L	.025	.036	.635	.914	
М	.045	.055	1.143	1.397	
N	.195	.205	4.953	5.207	
Р	.165	.185	4.191	4.699	
Q	.048	.054	1.219	1.372	
S	3°	6°	3°	6°	
Т	3°	6°	3°	6°	
U	3°	6°	3°	6°	
V	.094	.110	2.388	2.794	
W	.014	.025	.356	.635	
Х	3°	5.5°	3°	5.5°	
Υ	.385	.410	9.779	10.414	
Z	.130	.150	3.302	3.810	

NOTE:

1. Dimension L, M, W apply for Solder Dip Finish

Recommended Solder Pad Layout



TO-220-2

View A-A

Part Number	Package	Marking
C3D06060A	TO-220-2	C3D06060

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power_app_notes/soldering





Diode Model

$$\begin{array}{c|c} - & & \\ \hline V_T & R_T \end{array}$$

$$Vf_T = V_T + If * R_T$$

$$V_T = 0.96 + (T_J * -1.1*10^{-3})$$

 $R_T = 0.07 + (T_J * 7.4*10^{-4})$

Note: T_j = Diode Junction Temperature In Degrees Celsius, valid from 25°C to 175°C

Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body
nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited
to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical
equipment, aircraft navigation or communication or control systems, or air traffic control systems.

Related Links

- Cree SiC Schottky diode portfolio: http://www.cree.com/diodes
- Schottky diode Spice models: http://response.cree.com/Request_Diode_model
- SiC MOSFET and diode reference designs: http://response.cree.com/SiC_RefDesigns

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